

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Yushin TAKASAWA	06/10/2011
Hajime KARASAWA	06/10/2011
Yoshiro HIROSE	06/10/2011
RECEIVING PARTY DATA	
Name:	Hitachi Kokusai Electric Inc.
Street Address:	14-1, Sotokanda 4-chome
Internal Address:	Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	1018980
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13115578
CORRESPONDENCE DATA	
Fax Number:	(215)568-6499
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	215-568-6400
Email:	MDoogan@vklaw.com
Correspondent Name:	Volpe and Koenig, P.C.
Address Line 1:	30 South 17th Street
Address Line 2:	United Plaza
Address Line 4:	Philadelphia, PENNSYLVANIA 19103
ATTORNEY DOCKET NUMBER:	HITACHI12-21010089US01 MD
NAME OF SUBMITTER:	Melissa D. Doogan
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ASSIGNMENT

Yushin Takasawa, Hajime Karasawa, Yoshiro Hirose, residing at Toyama, Japan, citizens of Japan (hereafter the undersigned); are the inventor of Method of Manufacturing Semiconductor Device and Substrate Processing Apparatus for which the undersigned executed an application for United States Letters Patent, U.S. Patent Application No. 13/115,578, filed May 25, 2011.

The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

Hitachi Kokusai Electric Inc., [a / an] company, having a principal place of business at

14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan
(hereafter referred to as the assignee), is desirous of acquiring the entire right, title, and interest in said invention, all applications for, and all letters patent issued on said invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign, and transfer to the assignee and assignee's successors, assigns, and legal representatives the entire right, title, and interest in said invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, and all divisions and continuations thereof, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of

the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrants that the rights and property herein conveyed are free and clear of any encumbrance.

EXECUTED under seal on this 10th day of June, 2011

at Tokyo, Japan.
(Place)

Witness:

Yushin Takasawa (L.S.)
Yushin Takasawa

Hajime Karasawa (L.S.)
Hajime Karasawa

Yoshiro Hirose (L.S.)
Yoshiro Hirose

(Although not mandatory, if possible,
please subscribe appropriate notarization and obtain APOSTILLE)